

L Number	Hits	Search Text	DB	Time stamp
56	16548	bump near2 (electrode conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:28
57	4643787	via hole plug stud	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:29
58	7781	(bump near2 (electrode conduct\$3) ) and (via hole plug stud )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:29
59	531712	(dielectric insulat\$3) near (layer film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:30
60	3433	((bump near2 (electrode conduct\$3) ) and (via hole plug stud )) and ((dielectric insulat\$3) near (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:31
63	677	((bump near2 (electrode conduct\$3) ) and (via hole plug stud )) and ((dielectric insulat\$3) near (layer film))) and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:32